

Aurora Fact Sheet



System Feature	The Aurora Details	Comparison to Mira
Peak System Performance (FLOP/s)	180 - 450 PetaFLOP/s	10 PetaFLOP/s
Processor	Future Generation Intel® Xeon Phi™ Processor (Code name: Knights Hill)	PowerPC A2 1600 MHz processor
Number of Nodes	>50,000	49,152
Compute Platform	Intel system based on Cray Shasta next generation supercomputing platform	IBM Blue Gene/Q
Aggregate High Bandwidth On-Package Memory, local Memory and Persistent Memory	>7,000 Terabytes	768 Terabytes
Aggregate High Bandwidth On-Package Memory Bandwidth	>30 Petabytes/s	2.5 Petabytes/s
System Interconnect	2 nd Generation Intel® Omni-Path Architecture with silicon photonics	IBM 5D torus interconnect with VCSEL photonics
Interconnect Aggregate Node Link Bandwidth	>2.5 Petabytes/s	2 Petabytes/s
Interconnect Bisection Bandwidth	>500 Terabytes/s	24 Terabytes/s
Interconnect Interface	Integrated	Integrated
Burst Buffer Storage	Intel® SSDs, using both 1 st and 2 nd Generation Intel® Omni-Path Architecture	None
File System	Intel® Lustre File System	IBM GPFS File System
File System Capacity	>150 Petabytes	26 Petabytes
File System Throughput	>1 Terabyte/s	300 Gigabyte/s
Intel Architecture (Intel® 64) Compatibility	Yes	No
Peak Power Consumption	13 Megawatts	4.8 Megawatts
FLOP/s Per Watt	>13 GigaFLOP/s per watt	>2 GigaFLOP/s per watt
Delivery Timeline	2018	2012
Facility Area for Compute Clusters	~3,000 sq. ft.	~1,536 sq. ft.



For further information on Aurora, visit: intel.com/Aurora

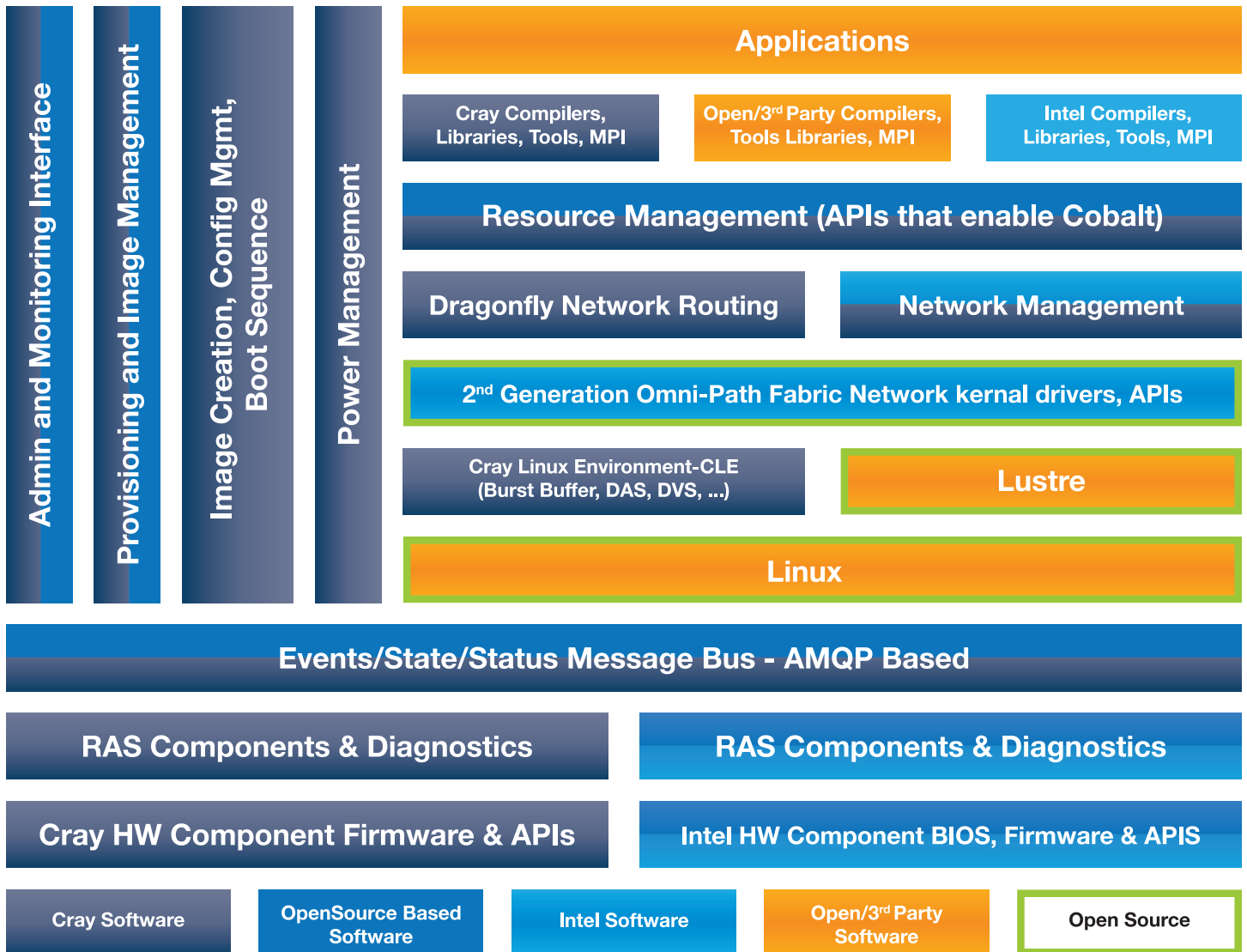
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Aurora's High Performance Software Stack



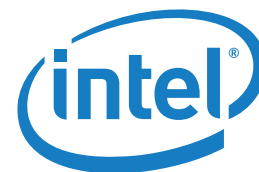
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Theta Fact Sheet

System Feature	The Theta Details
Peak System Performance (FLOPs)	>8.5 PetaFLOP/s
Compute Node CPU	Next Generation Intel® Xeon Phi™ Processors (Code name: Knights Landing) https://software.intel.com/en-us/articles/what-disclosures-has-intel-made-about-knights-landing
Compute Node Count	>2,500
Compute Platform	Intel system based on Cray XC supercomputing platform
Compute Node Peak Performance	>3 TeraFLOP/s per compute node
Cores Per Node	>60 cores with four hardware threads per core
High Bandwidth On-Package Memory	Up to 16 Gigabytes per compute node
High Bandwidth On-Package Memory Bandwidth	Projected to be 5X the bandwidth of DDR4 DRAM memory, >400 Gigabytes/sec
DDR4 Memory	192 Gigabytes using 6 channels per compute node
Lustre File System	10 Petabytes
Lustre File System throughput	210 Gigabytes/s
System Interconnect	Cray Aries high speed Dragonfly topology interconnect
Peak Power Consumption	1.7 Megawatts
Delivery Timeline	Mid-2016
Programming Environments	Intel, Cray, and GNU
Programming Models	MPI + OpenMP



To access further information, visit the following sites:

Argonne - www.anl.gov | Cray - www.cray.com | Intel - www.intel.com/hpc

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